

**MEC8-RA, MEC8-EM SERIES**

**(0.80 mm) .0315"**

# RIGHT ANGLE/EDGE MOUNT SOCKETS

Mates with:  
(1.60 mm) .062" thick card

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50µ" (1.27 µm) Ni  
**Operating Temp Range:** -55°C to +125°C  
**Insertion Depth:** (3.94 mm) .155" to (6.25 mm) .246"  
**Current Rating:** 2.0 A per pin (6 adjacent pins powered)  
**Voltage Rating:** 265 VAC  
**RoHS Compliant:** Yes  
**Lead-Free Solderable:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**MEC8** - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **RA1** - **OTHER OPTION**

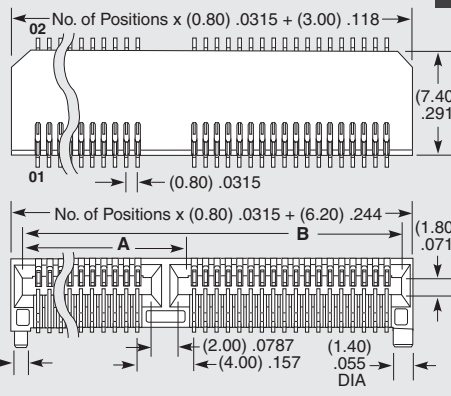
**Note:** Some sizes, styles and options are non-standard, non-returnable.

**10, 13, 20, 25, 30, 37, 40, 49, 50**

**-L**  
= 10µ" (0.25 µm) Gold on contact, Matte Tin on tail

**-TR**  
= Tape & Reel Packaging

POS. PER ROW	A	B
13	(6.10) .240	(15.00) .591
25	(18.10) .713	(34.20) 1.346
37	(18.90) .744	(36.60) 1.441
40	(18.90) .744	(36.60) 1.441
49	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756



MEC8-RA	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	9.5 GHz / 19 Gbps

\*Test board losses de-embedded from performance data.  
Complete test data available at [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA) or contact sig@samtec.com

**ALSO AVAILABLE (MOQ Required)**

- 1 mm mating card thickness option
- Latching option
- Elevated Contact Samtec.

Mates with:  
(1.60 mm) .062" thick card

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-EM](http://www.samtec.com?MEC8-EM)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50µ" (1.27 µm) Ni  
**Operating Temp Range:** -55°C to +125°C  
**Insertion Depth:** (4.32 mm) .170" to (5.66 mm) .223"  
**Current Rating:** 1.8 A per pin (6 adjacent pins powered)  
**Voltage Rating:** 265 VAC  
**RoHS Compliant:** Yes  
**Lead-Free Solderable:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

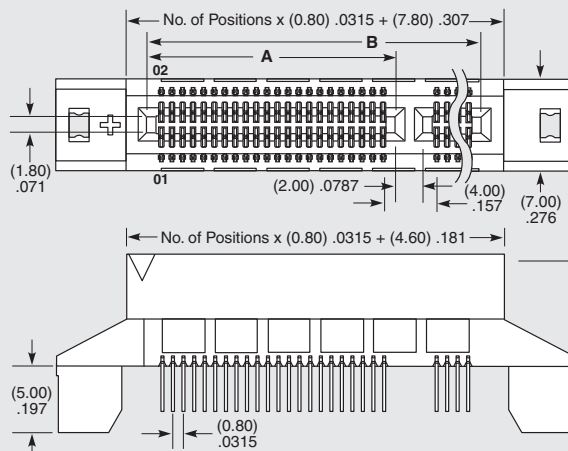


**MEC8** - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **EM2**

**10, 20, 30, 40, 50, 60, 70**

**-L**  
= 10µ" (0.25 µm) Gold on contact, Matte Tin on tail

**EM2**  
= (1.60 mm) .062" thick PCB



MEC8-EM	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	9.5 GHz / 19 Gbps
Differential Pair Signaling	9 GHz / 18 Gbps

\*Test board losses de-embedded from performance data.  
Complete test data available at [www.samtec.com?MEC8-EM](http://www.samtec.com?MEC8-EM) or contact sig@samtec.com

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70	(30.90) 1.217	(60.60) 2.386

**ALSO AVAILABLE (MOQ Required)**

- 1 mm mating card thickness option

Contact Samtec.